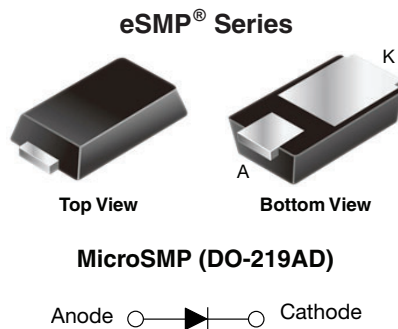


Surface-Mount TMBS[®] (Trench MOS Barrier Schottky) Rectifier



MicroSMP (DO-219AD)

FEATURES

- Very low profile - typical height of 0.65 mm
- Ideal for automated placement
- Trench MOS Schottky technology
- Low forward voltage drop
- Low power loss, high efficiency
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified available
- Automotive ordering code: base P/NHM3
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



LINKS TO ADDITIONAL RESOURCES



[3D Models](#)

PRIMARY CHARACTERISTICS

$I_{F(AV)}$	2 A
V_{RRM}	100 V
I_{FSM}	30 A
V_F at $I_F = 2$ A (125 °C)	0.62 V
T_J max.	175 °C
Package	MicroSMP (DO-219AD)
Circuit configuration	Single

TYPICAL APPLICATIONS

For use in low voltage high frequency inverters, freewheeling, DC/DC converters, and polarity protection applications, in commercial, industrial, and automotive applications.

MECHANICAL DATA

Case: MicroSMP (DO-219AD)

Molding compound meets UL 94 V-0 flammability rating
 Base P/N-M3 - halogen-free, and RoHS-compliant
 Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

Terminals: matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 and HM3 suffix meets JESD 201 class 2 whisker test

Polarity: color band denotes the cathode end

MAXIMUM RATINGS ($T_A = 25$ °C unless otherwise noted)

PARAMETER	SYMBOL	V2PM10	UNIT
Device marking code		2MB	
Maximum repetitive peak reverse voltage	V_{RRM}	100	V
Maximum DC forward current	$I_{F(AV)}$ ⁽¹⁾	1.5	A
	$I_{F(AV)}$ ⁽²⁾	2	A
Peak forward surge current 10 ms single half sine-wave superimposed on rated load	I_{FSM}	30	A
Operating junction and storage temperature range	T_J ⁽³⁾ , T_{STG}	-40 to +175	°C

Notes

⁽¹⁾ Free air, mounted on recommended copper pad area

⁽²⁾ Mounted on 8.0 mm x 8.0 mm pad area

⁽³⁾ The heat generated must be less than the thermal conductivity from junction to ambient: $dP_D/dT_J < 1/R_{\theta JA}$

ELECTRICAL CHARACTERISTICS ($T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage	$I_F = 1.0\text{ A}$	$T_A = 25\text{ }^\circ\text{C}$	$V_F^{(1)}$	0.61	-	V
	$I_F = 2.0\text{ A}$	$T_A = 25\text{ }^\circ\text{C}$		0.75	0.83	
	$I_F = 1.0\text{ A}$	$T_A = 125\text{ }^\circ\text{C}$		0.53	-	
	$I_F = 2.0\text{ A}$	$T_A = 125\text{ }^\circ\text{C}$		0.62	0.7	
Reverse current	$V_R = 70\text{ V}$	$T_A = 25\text{ }^\circ\text{C}$	$I_R^{(2)}$	0.001	-	mA
		$T_A = 125\text{ }^\circ\text{C}$		0.25	-	
	$V_R = 100\text{ V}$	$T_A = 25\text{ }^\circ\text{C}$		-	0.05	
		$T_A = 125\text{ }^\circ\text{C}$		0.5	2	
Typical junction capacitance	4.0 V, 1 MHz		C_J	150	-	pF

Notes

- (1) Pulse test: 300 μs pulse width, 1 % duty cycle
 (2) Pulse test: pulse width $\leq 5\text{ ms}$

THERMAL CHARACTERISTICS ($T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)			
PARAMETER	SYMBOL	V2PM10	UNIT
Typical thermal resistance	$R_{\theta JA}^{(1)(2)}$	130	$^\circ\text{C/W}$
	$R_{\theta JM}^{(3)}$	20	

Notes

- (1) The heat generated must be less than the thermal conductivity from junction-to-ambient: $dP_D/dT_J < 1/R_{\theta JA}$
 (2) Free air, mounted on FR4 PCB, 2 oz. standard footprint, $R_{\theta JA}$ - junction to ambient
 (3) Mounted on PCB with 8.0 mm x 8.0 mm copper pad areas, $R_{\theta JM}$ - junction to mount

ORDERING INFORMATION (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
V2PM10-M3/H	0.006	H	4500	7" diameter plastic tape and reel
V2PM10HM3/H ⁽¹⁾	0.006	H	4500	7" diameter plastic tape and reel

Note

- (1) AEC-Q101 qualified

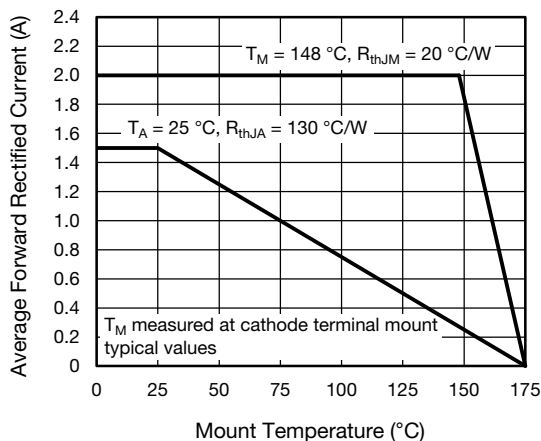
RATINGS AND CHARACTERISTICS CURVES ($T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)


Fig. 1 - Maximum Forward Current Derating Curve

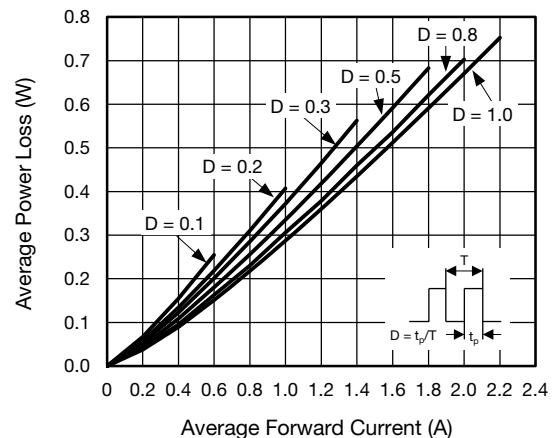


Fig. 2 - Average Power Loss Characteristics

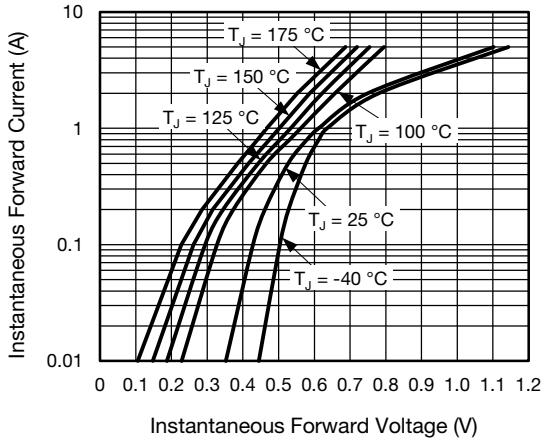


Fig. 3 - Typical Instantaneous Forward Characteristics

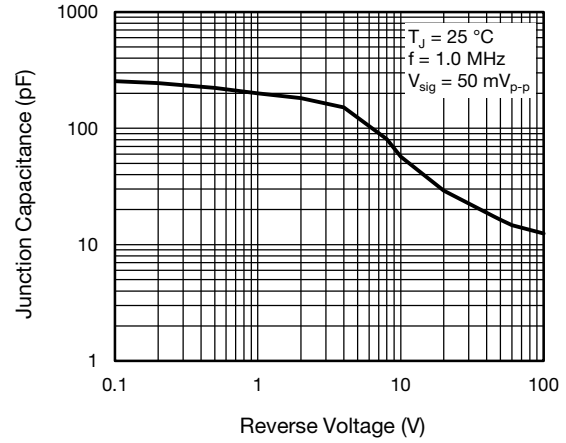


Fig. 5 - Typical Junction Capacitance

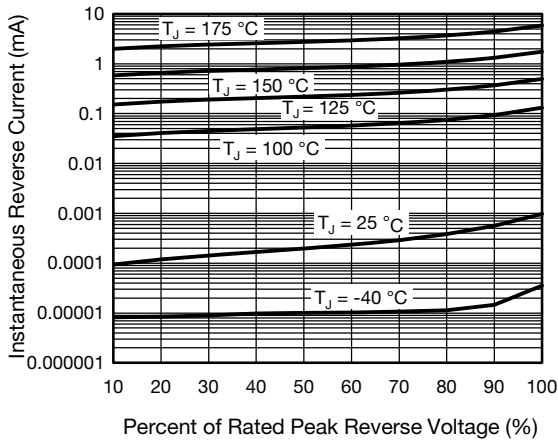


Fig. 4 - Typical Reverse Leakage Characteristics

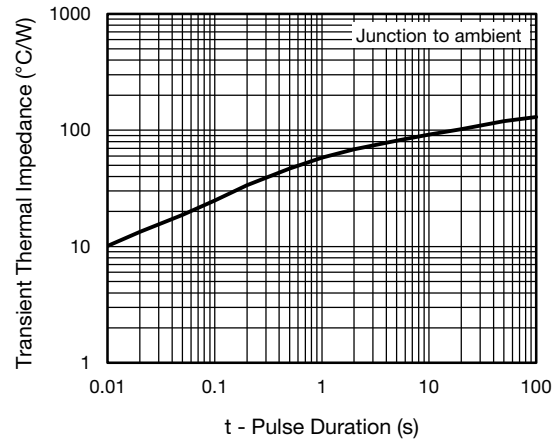
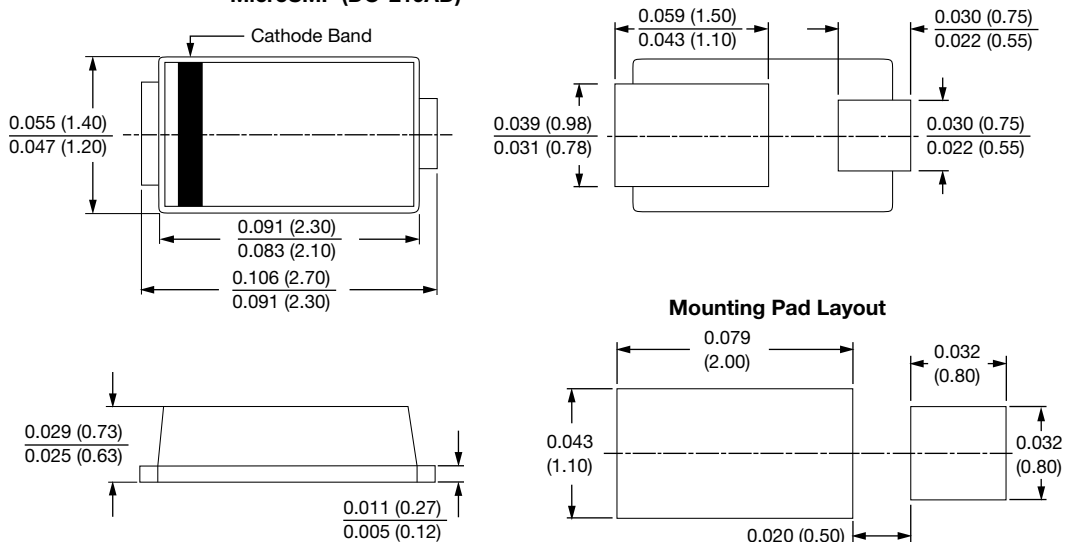


Fig. 6 - Typical Transient Thermal Impedance

PACKAGE OUTLINE DIMENSIONS in inches (millimeters)

MicroSMP (DO-219AD)





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